



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of: Chakravarthi et al.

Docket No.: TI-33161

Serial No.: 10/020,813

Art Unit: 2813

Filed: 12/12/01

Examiner: Huynh, Yennhu

Title: Fabrication of Ultra Shallow Junctions From a Solid Source With Fluorine

Implantation

SECOND REPLY UNDER 37 CFR §1.111

April 2, 2004

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Dear Sir:

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)

I hereby certify that the above correspondence is being deposited 4-2-04 with the U.S. Postal Service on

as First Class Mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450

In response to the Office Action, dated 01/07/2004, in the above-identified patent application, please make the following amendments. They are respectfully submitted as a full and complete response to that Action. Charge any required fees to the deposit account of Texas Instruments Incorporated, Account No. 20-0668.